TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2776

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain—source ON resistance : RDS (ON) = 0.75Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 7.0 S$ (typ.) • Low leakage current : $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 500 V$) • Enhancement mode : $V_{th} = 2.0 \sim 4.0 V$ ($V_{DS} = 10 V$, $I_{D} = 1 mA$)

Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	500	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	ID	8	Α	
	Pulse (Note 1)	I _{DP}	32	А	
Drain power dissipation (Tc = 25°C)		PD	65	W	
Single pulse avalanche energy (Note 2)		E _{AS}	312	mJ	
Avalanche current		I _{AR}	8	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	6.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.92	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

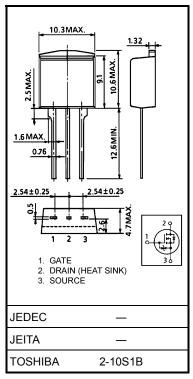
Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 8.3 mH, R_G = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

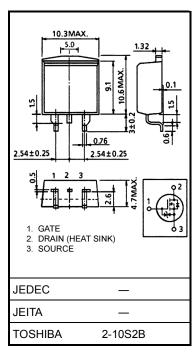
This transistor is an electrostatic-sensitive device.

Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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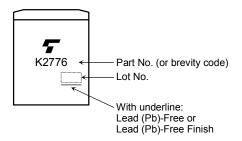
Electrical Characteristics (Ta = 25°C)

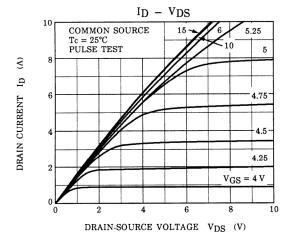
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	_	_	V
Gate threshold v	roltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A	_	0.75	0.85	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 4 A	3.5	7.0	_	S
Input capacitano	:e	C _{iss}			1300	_	
Reverse transfe	r capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	130	_	pF
Output capacita	Output capacitance C _{oss}		_	400	_		
Switching time	Rise time	t _r	V _{GS} _{0V} R _L =50Ω	_	26	_	ns
	Turn-on time	t _{on}		_	45	_	
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}	$V_{DD} = 200V$ Duty $\leq 1\%$, $t_{W} = 10 \mu s$	_	140	_	
Total gate charg plus gate-drain)		Qg			30	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}$		17	_	nC
Gate-drain ("mil	e-drain ("miller") Charge Q _{gd}			13	_		

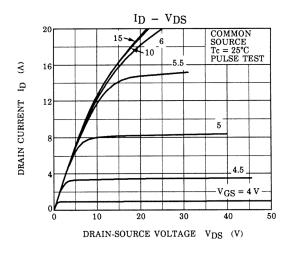
Source-Drain Ratings and Characteristics (Ta = 25°C)

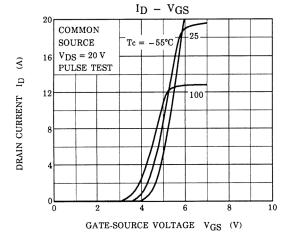
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	8	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	32	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 8 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 8 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / μs	_	1200	_	ns
Reverse recovery charge	Q _{rr}		- 1	10	_	μC

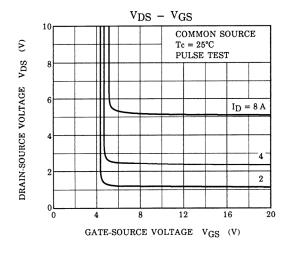
Marking

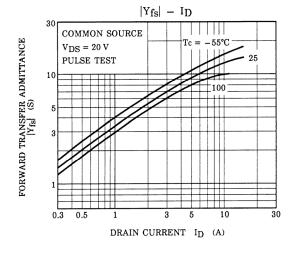


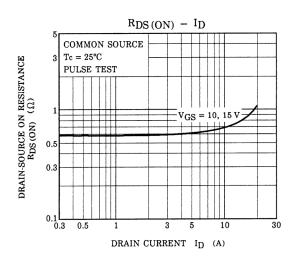


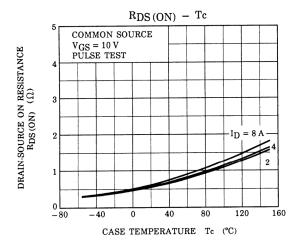


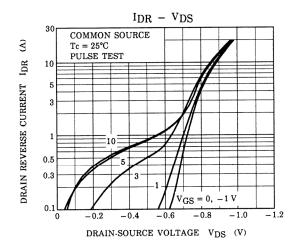


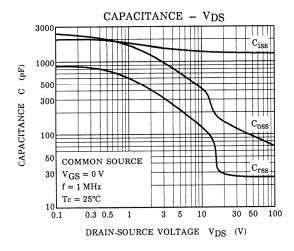


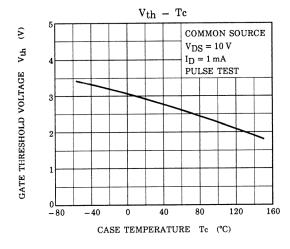


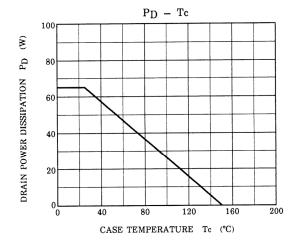


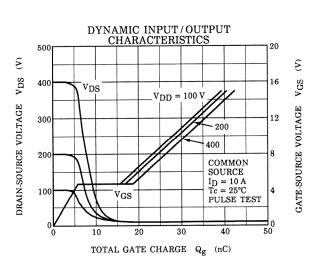




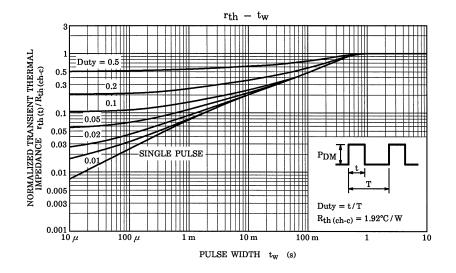


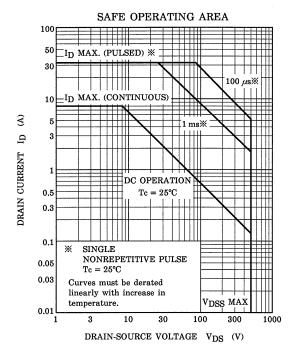


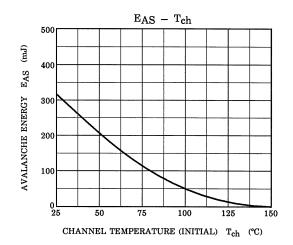


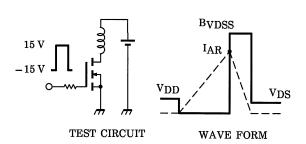


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$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V}, L = 8.3 \text{ mH}$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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